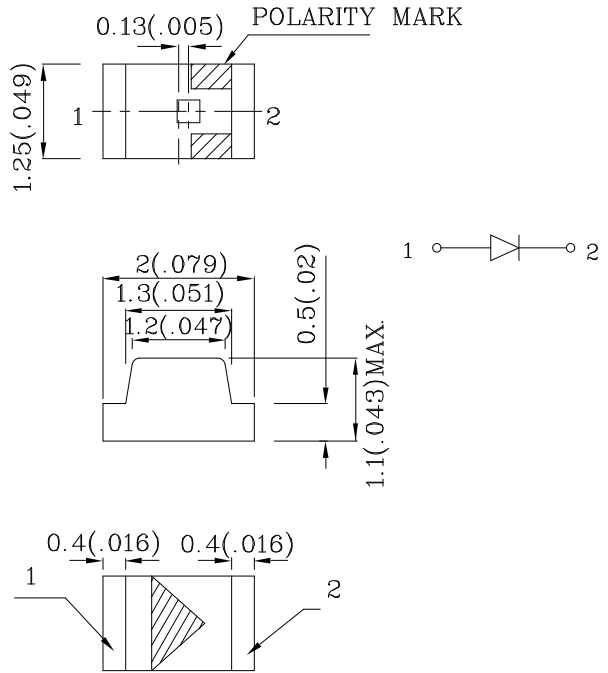


Features

- 2.0mmx1.25mm SMT LED,1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



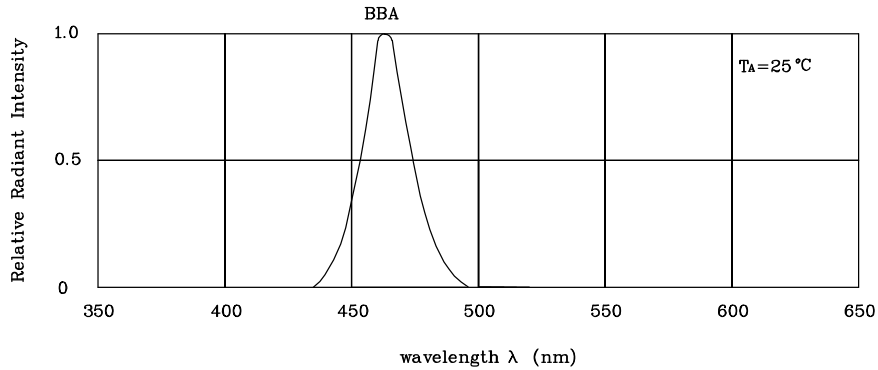
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.1(0.004)$ " unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute maximum ratings ($T_A=25^\circ\text{C}$)		BBA (InGaN)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	100	mA
Power Dissipation	P_T	120	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

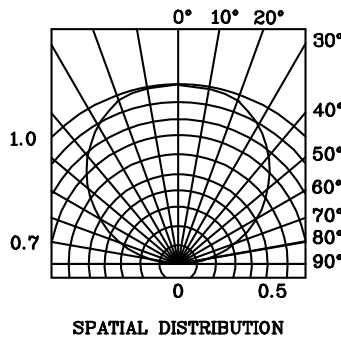
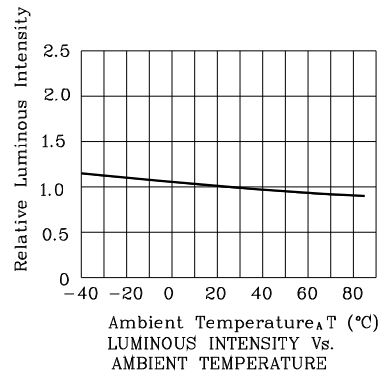
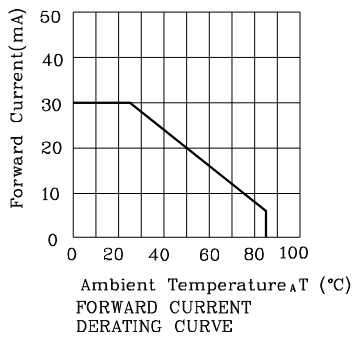
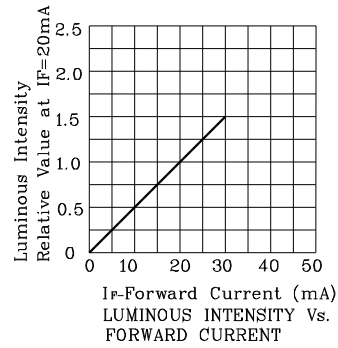
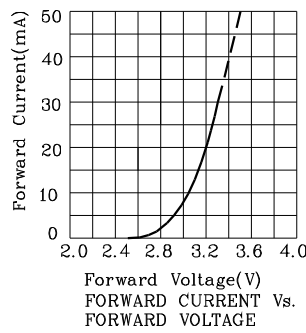
Operating Characteristics ($T_A=25^\circ\text{C}$)		BBA (InGaN)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	3.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	4.0	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	468	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	21	nm
Capacitance ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ
				min.	typ.		1/2
XZBBA54W	Blue	InGaN	Water Clear	18	59	468	120°

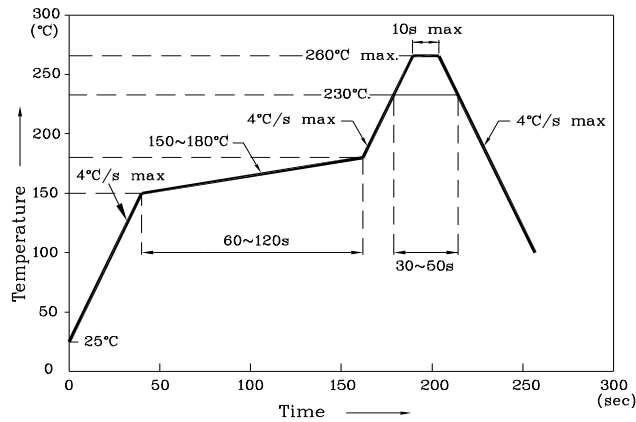


RELATIVE INTENSITY Vs. WAVELENGTH

❖ BBA



Reflow Soldering Profile For Lead-free SMT Process.

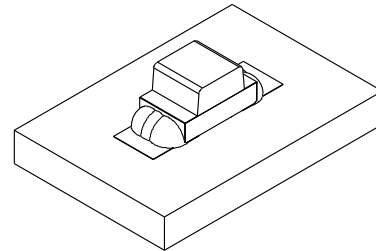
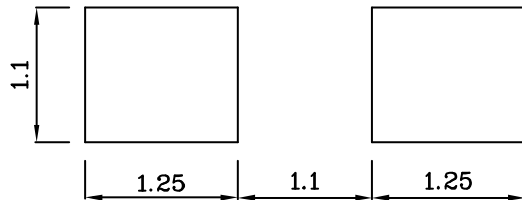


Notes:

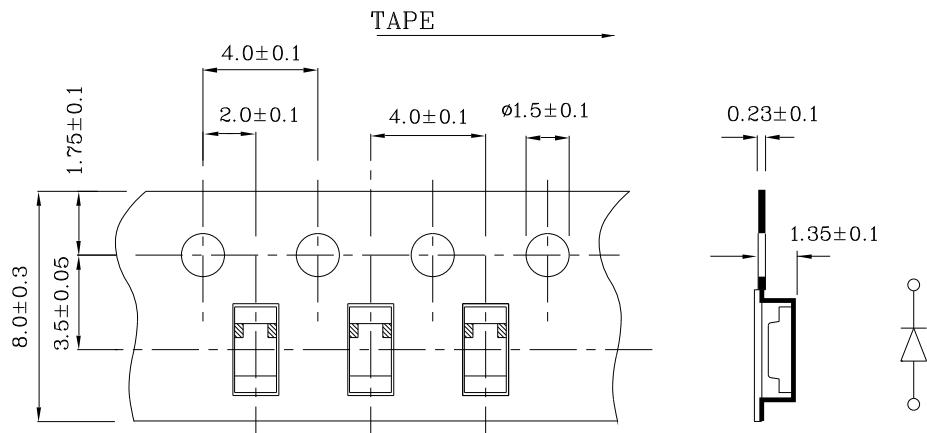
1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern
(Units: mm ; Tolerance: ± 0.1)

❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

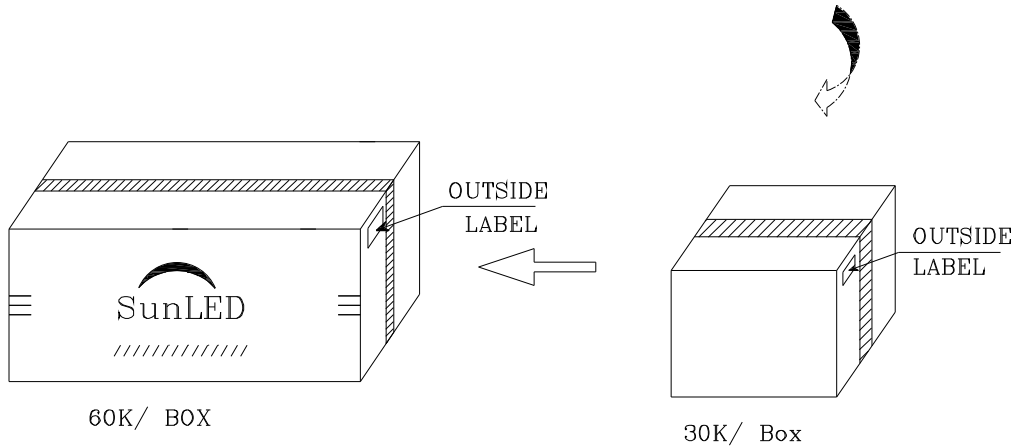
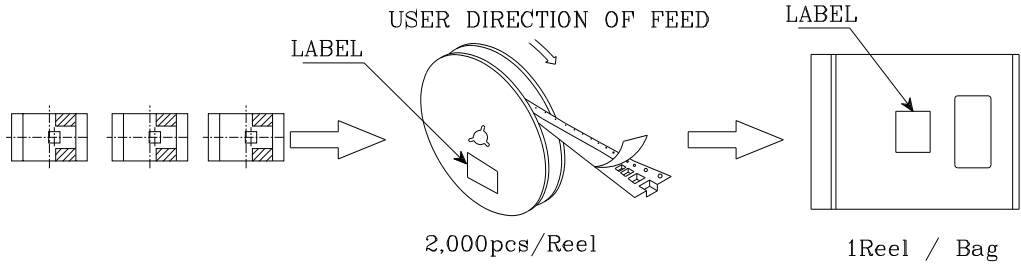

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

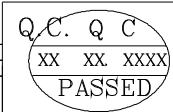

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy May Depend on The sorting Parameters.

PACKING & LABEL SPECIFICATIONS

XZBBA54W

	
P/NO : XZxxx54x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	